

## PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1  
Stylesheet Version v1.2

EPAS ID: PAT3944080

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
DEYUAN XIAO	06/15/2016
RICHARD R. CHANG	06/16/2016
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	ZING SEMICONDUCTOR CORPORATION
<b>Street Address:</b>	3RD FLOOR, NO.15, ALY. 1412, YUNDUAN RD.
<b>Internal Address:</b>	NICHENG TOWN, PUDONG NEW AREA
<b>City:</b>	SHANGHAI
<b>State/Country:</b>	CHINA
<b>Postal Code:</b>	201306
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
Application Number:	15198805
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(719)623-0141
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
<b>Phone:</b>	719-475-7103
<b>Email:</b>	PTOHLG@me.com
<b>Correspondent Name:</b>	HUFFMAN LAW GROUP, P.C.
<b>Address Line 1:</b>	7702 BARNES RD., STE. 140-46
<b>Address Line 4:</b>	COLORADO SPRINGS, COLORADO 80922
<b>ATTORNEY DOCKET NUMBER:</b>	ZING-50150964US
<b>NAME OF SUBMITTER:</b>	TAYSIE J. LOCKE
<b>SIGNATURE:</b>	/Taysie J. Locke/
<b>DATE SIGNED:</b>	06/30/2016
This document serves as an Oath/Declaration (37 CFR 1.63).	
<b>Total Attachments: 2</b>	
source=ZING-50150964US_DecAssignment#page1.tif	
source=ZING-50150964US_DecAssignment#page2.tif	

**DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN  
APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT FOR SINGLE  
ASSIGNEE**

<b>TITLE OF INVENTION</b>	<b>SOI SUBSTRATE AND MANUFACTURING METHOD THEREOF</b>
---------------------------	---

This is a combined declaration and assignment by the inventor(s) named below to the assignee named below.

**I. Declaration and Related Statements**

As a below named inventor, I hereby declare that:

This declaration is directed to:

The attached application; or

United States application or PCT International application number \_\_\_\_\_  
filed on \_\_\_\_\_.

The above-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

**II. Assignment**

WHEREAS, I, the undersigned inventor (or one of the undersigned joint inventors), having invented certain new and useful improvements as below entitled, for which application for United States Letters Patent is made, the said application having been executed on even date herewith;

**AND WHEREAS, Zing Semiconductor Corporation**

together with any successors, legal representatives, or assigns thereof, with its principal office at 3rd Floor, No. 15, Aly. 1412, Yunduan Rd., Nicheng Town, Pudong New Area, Shanghai, PRC, 201306, wants to acquire the entire right, title and interest in and to the said invention(s), and to the said application and any Letters Patent that may issue thereon;

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I have sold, assigned, transferred and set over, and do hereby sell, assign, transfer and set over to the said **Zing Semiconductor Corporation**, its successors and assigns, the entire right, title and interest in and to the said invention and in and to the said application and all patents which may be granted thereon, and all divisions, reissues, substitutions, continuations, and extensions thereof; and I/we hereby authorize and request the Commissioner of Patents, and any officials of foreign countries whose duty it is to issue patents on applications, to issue all patents for said invention, or patents resulting therefrom, insofar as my interest in concerned, to the said **Zing Semiconductor Corporation** as assignee of my entire right, title and interest;


I ALSO HEREBY sell and assign to **Zing Semiconductor Corporation**, its successors and assigns, my foreign rights to the invention disclosed in said application, in all countries of the world, including the right to file applications and obtain patents under the terms of the International Convention for the Protection of Industrial Property, and of the European Patent Convention, and further agree to execute any and all patent applications, assignments, affidavits, and any other papers in connection therewith necessary to perfect such patent rights;


AND I HEREBY covenant that I have full right to convey the entire interest herein assigned, and that I have not executed, and will not execute, any agreement in conflict herewith;

AND I HEREBY further covenant that I will communicate to said **Zing Semiconductor Corporation**, or to its successors, assigns and legal representatives, any facts known to me respecting said invention, and at the expense of said **Zing Semiconductor Corporation**, testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, reissue and substitute applications, make all lawful oaths, and generally do everything possible to aid said **Zing Semiconductor Corporation**, its successors, assigns and nominees to obtain and enforce proper patent protection for said invention in all countries.

### III. Signatures

#### A. Inventors

Signature: 	Date: <i>June 15, 2016</i>
Deyuan Xiao	

Signature: 	Date: <i>6/16/2016</i>
Richard R. Chang	